

Fair-Rite P/N 2508056007Y3

Y Chip Bead Material Grade

Nominal Chemical Composition

Supporting notes:

1. P/N 2508056007Y3 consists of:
 - a core Y Chip Bead Material Grade
 - b Termination Plating SnNiAg
2. Moisture Sensitivity Level (MSL)= 1
3. Max Reflow Temp= 260 degC
4. Max Time at Max Reflow Temp= 40 sec
5. RoHS 6/6 Compliant Terminations/ Wire are backwards compatible with standard Soldering Processes
6. RoHS Conversion Date= 1/1/2005
7. RoHS Compliance Marking is Contained on Shipping Labels

			Wt of core (g)=	
<u>Ferrite -Compound</u>	<u>CAS Number</u>	<u>wt %</u>	0.008	
Fe2O3	1309-37-1	65	0.0052	Compound Weight (g) Breakdown of Y Chip Bead Material Grade
ZnO	1314-13-2	17	0.0014	
NiO	1313-99-1	9	0.0007	
CuO	1317-38-0	6	0.0005	
MnO	1344-43-0	3	0.0002	

			Wt of termination (g)=	
<u>Termination Plating - Elements</u>	<u>CAS Number</u>	<u>wt %</u>	0.002	
Sn	7440-31-5	14.3	0.000286	Element Weight (g) Breakdown of Pb- Free Termination Plating
Ni	7440-02-0	6.9	0.000138	
Ag	7440-22-4	78.8	0.001576	

Calculated Maximum Levels of RoHS Restricted Substances Present in Y Chip Bead Material Grade

			Wt of core (g)=	
<u>Impurity Substance</u>	<u>RoHS Threshold (ppm):</u>	<u>ppm</u>	0.008	
Cr+6	1000	0	0	RoHS Impurity Substance Weight (g) Breakdown of Y Chip Bead Material Grade
Cd	100	0	0	
Hg	1000	0	0	
Pb	1000	0	0	
PBB	1000	0	0	
PBDE	1000	0	0	
Bis(2-Ethylhexyl) phthalate (DEHP)	1000	0	0	
Benzyl butyl phthalate (BBP)	1000	0	0	
Dibutyl phthalate (DBP)	1000	0	0	
Diisobutyl phthalate (DIBP)	1000	0	0	